

**DECLARATION**(Original, Design, National Stage of PCT  
or CIP Application)**ATTORNEY'S DOCKET NO.**

34282

As a below named inventor I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name, I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

**METHOD OF CREATING MULTI-LAYERED MONOLITHIC CIRCUIT STRUCTURE CONTAINING INTEGRAL BURIED AND TRIMMED COMPONENTS**

the specification of which: (complete (a), (b) or (c) for type of application)

**REGULAR OR DESIGN APPLICATION**(a) ☒ is attached hereto.(b) ☐ was filed on \_\_\_ as Application Serial No. \_\_\_ and was amended on \_\_\_\_\_ (if applicable).**PCT FILED APPLICATION ENTERING NATIONAL PHASE**(c) ☐ was described and claimed in International Application No. \_\_\_\_\_ filed \_\_\_\_\_ and as amended on \_\_\_\_\_ (if any).**ACKNOWLEDGMENT OF REVIEW OF PAPERS AND DUTY OF CANDOR**

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56(a).

☐ In compliance with this duty there is attached an information disclosure statement. 37 CFR 1.97.

**PRIORITY CLAIM**

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:  
(complete (d) or (e))

(d) ☒ no such applications have been filed.(e) ☐ such applications have been filed as follows**EARLIEST FOREIGN APPLICATION(S), IF ANY FILED WITHIN 12 MONTHS PRIOR TO SAID APPLICATION**

Country	Application No.	Date of Filing	Date of Issue	Priority Claimed
				<input type="checkbox"/> YES <input type="checkbox"/> NO
				<input type="checkbox"/> YES <input type="checkbox"/> NO
				<input type="checkbox"/> YES <input type="checkbox"/> NO

**ALL FOREIGN APPLICATION(S), IF ANY FILED MORE THAN 12 MONTHS PRIOR TO SAID APPLICATION**


**PROVISIONAL**

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States application(s) listed below:

Application Serial No.	Filing Date	Status (patented, pending, abandoned)
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**CONTINUATION-IN-PART**

(Complete This Part Only If This Is A Continuation-In-Part Application)

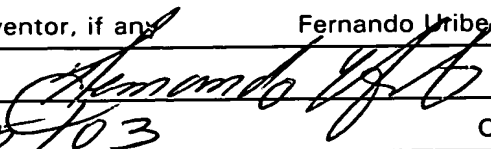
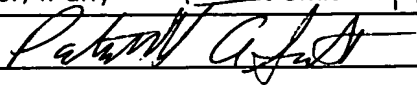
I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose to the Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56(a), which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application:

Application Serial No.	Filing Date	Status (patented, pending, abandoned)
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Application Serial No.	Filing Date	Status (patented, pending, abandoned)
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor		Roy J. Blazek
Inventor's Signature <i>Roy J. Blazek</i>		
Date	2/12/04	Country of Citizenship United States
Residence		5600 West 92nd Place, Overland Park, Kansas 66207
Post Office Address		5600 West 92nd Place, Overland Park, Kansas 66207
Full name of second joint inventor, if any		Gregory Eugene Barner
Inventor's Signature <i>Gregory Eugene Barner</i>		
Date	2/12/04	Country of Citizenship United States
Residence		12909 West 118th Terrace, Overland Park, Kansas 66210
Post Office Address		12909 West 118th Terrace, Overland Park, Kansas 66210
Full name of third joint inventor, if any		Sam William Bandler
Inventor's Signature <i>Sam Bandler</i>		
Date	2/12/04	Country of Citizenship United States
Residence		16320 South Avalon Street, Olathe, Kansas 66062
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Full name of fourth inventor, if any		Eric Eubank
Inventor's Signature <i>Eric Eubank</i>		
Date	02/12/04	Country of Citizenship United States
Residence		202 NW Gibson Court, Lee's Summit, Missouri 64063

Post Office Address	202 NW Gibson Court, Lee's Summit, Missouri 64063		
Full name of fifth inventor, if any	Fernando Uribe		
Inventor's Signature			
Date	12/15/03	Country of Citizenship	United States
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Full name of sixth inventor, if any	<del>Pat Smith</del> Patrick A. Smith		
Inventor's Signature			
Date	12/3/03	Country of Citizenship	United States
Residence	12905 Granite NE, Albuquerque, New Mexico 87112		
Post Office Address	12905 Granite NE, Albuquerque, New Mexico 87112		

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

Application of: )  
)  
BLAZEK, Roy J. et al. ) Examiner:  
)  
Serial No.: ) Group Art Unit  
)  
Filed: )  
)  
METHOD OF CREATING MULTI-LAYERED )  
MONOLITHIC CIRCUIT STRUCTURE CONTAINING )  
INTEGRAL BURIED AND TRIMMED COMPONENTS )

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Mail Stop: Patent Application  
Commissioner For Patents  
Post Office Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

POWER OF ATTORNEY

The Owner, (hereinafter "Assignee"), of the entire right, title, and interest in the above-referenced application is Honeywell Federal Manufacturing & Technologies, LLC, 2000 East Bannister Road, Kansas City, Missouri 64131. The undersigned, , has the authority to sign on behalf of Assignee.

An assignment of the above-referenced application from the inventors, Roy J. Blazek; Gregory Eugene Barner; Sam William Bandler; Eric Eubank; Fernando Uribe; and Pat Smith, to Assignee is attached hereto.

Assignee hereby appoints the following individuals as its attorneys for the purpose of receiving all future correspondence in connection with said patent application and transacting all business in the United States Patent and Trademark Office with respect to said patent application:

Robert D. Hovey	19,228	Tracey S. Truitt	43,205
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HONEYWELL FEDERAL MANUFACTURING & TECHNOLOGIES, LLC

By:

\_\_\_\_\_

Feb 10, 2004

(DOCKET NO. 34282)